

Advanced Optical Alignment WDS750 BGA Reballing Machine with 3 **Independent Heating Zones**

Basic Information

- Place of Origin:
- WDS • Brand Name:
- Certification:
- Model Number:
- Minimum Order Quantity: 1 UNIT
- Packaging Details:
- Delivery Time:
- Payment Terms:
- Supply Ability:
- Wooden case 3-5 working days
- T/T, Western Union, MoneyGram
- 150 UNITS PER MONTH

China

CE

WDS-750



Product Specification

Model:	WDS-750
 Total Power Supply: 	7200W
 Upper Heating Power Supply: 	1600W
 Lower Heating Power Supply: 	1200W
• IR Heating Power Supply:	4200W(2400W Controlled)
Highlight:	WDS-750 BGA Work Station,

n, Temperature Control System BGA Work Station , Auto Laptop BGA Machine



More Images



Product Description

WDS-750 Optical Alignment BGA Rework Station High temperature control system

Features:

1. Touch screen interface, heating time, heating temp, temp rise speed, cooling time, alarm advance, vacuum time are set up inside the touch screen, easy to use;

2.Panasonic PLC, independent control temperature control module, shows 3 temp curves all the time,4 independent sensors, check the temp accurately for the chip points, ensure the weld yield;

3.3 independent heating zones, each heating zone can set up the heating temp, heating time, temp rise rate; Six period of heating temperature, simulate the reflow heating mode, set up as Preheating, keeping, heating, welding, welding, cooling;

4. Auto feed chip, auto pick up chip, auto blowing chip, can identify the central position automatically when optical alignment;

5.Multifunction mode choice, four modes as weld, remove, mount, manual, automatic and semi-auto function, meet the various needs of the users:

6.Uses the high precision K-type thermocouple closed-loop control which is imported from USA, with the unique heating method, ensure the weld temp precision control within ±1 °C

7.Uses imported optical alignment system, 500 pixel HD camera, HDMMI HD signal output, 15 inch HD LCD, high accurate micrometer X/Y/Z axis adjustment, ensure the location precision within 0.01-0.02mm;

8. The upper heating head and placement head are designed 2 in 1, different size of heating nozzles are provided, easy to remove and install, can be customized, meet the more requirement for users;

9. High automation and precision to avoid artificial error fully, can make the best repairing effect for the lead free technology,double-deck BGA,QFN,QFP,capacitance resistance and other components and parts;

10.Equipped the extra camera to obverse the solder ball melting to ensure the temp curve and weld effect(this function is optional).

WDS-750 parameter:

Upper heating power1600WBottom heating power1200WBottom IR heating power4200W(2400W is controlled)Power supply(Single Phase) AC 220V±10 50HzLocation wayOptical camera+ V-shape card slot + laser position for fast locationTemperature controlHigh precision K sensor closed loop control,independent temperature control with ±1 °C precisionAppliance selectionHigh sensitive touch screen + temperature control mode +Panasonic PLC +step driverMax. PCB size570×480mmMin. PCB size10×10mmSensor4unitsChip amplification multiple1-200XPCB thickness0.5-8mmChip size0.15mmMax. mount loading500GMount precision±0.01mmOverall sizeL670×W780×H850mmOptical cameraCan be removed front and back,left and right,prevent the dead angle		
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dead angle	Overall size	L670×W780×H850mm
Machine weight 75kg	Optical camera	
	Machine weight	75kg



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